

ABSTRACT

Some embodiments of a method and apparatus for cooling integrated circuit devices are described. In one embodiment, the apparatus includes a thermosiphon having an evaporator portion coupled to a first surface of a heat source and a condenser portion coupled to the evaporator portion distal from the first surface of the heat source. A remote heat exchanger is coupled to the condenser of the thermosiphon. In addition, one or more thermoelectric elements are coupled between the heat exchanger and the condenser of the thermosiphon. In one embodiment, the remote heat exchanger, the thermoelectric elements and the condenser portion of the thermosiphon are located outside a chassis of a one rack unit (1U) server computer.